JAN 2 2 2004 SIN THE UNITED STATES PATENT AND TRADEMARK OFFICE (213.003-US)

in re Application of: YE ET AL.

Serial No: 10/677,563

Filed: OCTOBER 2, 2003

Title: METHOD AND APPARATUS FOR MONITORING)

INTEGRATED CIRCUIT FABRICATION

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

Group Art Unit:

Examiner:

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail with sufficient postage in an envelope addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on MINIARY TO, 2004

(person signing this certificate)

Signature

SECOND INFORMATION DISCLOSURE STATEMENT

Dear Sir:

Submitted herewith are three (3) sheets of a modified Form PTO-1449. A copy of each document cited on the attached Form PTO-1449 is also submitted.

It is respectfully requested that the Examiner make his/her consideration of these documents formally of record with the initial Office Action.

Respectfully submitted,

Date: January 20, 2004

Neil A. Steinberg Reg. No. 34,735

650-968-8079

PTO-1449 (Modified)

U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE 253.003-US

SERIAL NUMBER 10/677,563

Ye et al.

INFORMATION DISCLOSURE STATEMENT BY APPLICANT

FILING DATE

GROUP ART UNIT

October 2, 2003

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EXAMINER INITIALS	DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS	FILING DATE
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PTO-1449 Modified)

U.S. DEPARTMENT COMMERCE PATENT AND TRADEMARK BASES

ATTY. DOCKET NO. 213.003-US SERIAL NUMBER 10/677,563

APPLICANT(S)

Ye et al.

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Sheet 3 of 3

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